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Released on April 9, 2003

Yokowo Corporation
"Vertical Probe Card for wafer testing" Released

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■Summary

Yokowo Corporation has completed the development of its Vertical Probe Card for wafer testing, using Yokowo's own gold alloy probe plungers.

■Background

Over the last few years, the standard technique of connecting silicon die to substrate by wire bonding has evolved into other techniques to meet the requirements of high speed digital and radio frequency signal transmission. Flip Chip and Chip Scale Packaging are two examples of this evolution towards direct bonding of the die to the substrate using solder balls. We expect that this trend will continue.

Yokowo Corporation, using its expertise in micro technology and design, successfully developed this new Vertical Probe Card to meet the growing demand for tools to test at the wafer level.

■Outline of " Vertical Probe Card "

Advantages of Yokowo's Vertical Probe Card are as follows:

- Contact spring probes are more durable than other methods of contacting wafer level solder balls for test
- The gold alloy plunger in Yokowo's pins eliminates plating related issues
- Vertical probe application allows for easy testing of solder balls scattered randomly or in array
- Yokowo offers vertical probes for ball spacing (pitch) from 120 microns to 400 microns
- The tip style of Yokowo's probes, and also the low spring force, prevents unnecessarily deep witness marks
- The gold alloy allows for the pin to return to its original condition after cleaning

■Our future plan

Yokowo is pleased to announce that the evaluation of this product is complete, and orders have been received from several customers. Sales of this product are expected to reach roughly $1,000,000 during 2003 and $2,000,000 in 2004.

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